

客户 Customer: _____

日期 Date: _____

纳入仕様书 SPECIFICATION

产 品 名 称 PRODUCT NAME: 叠层片式耦合器

Multilayer Chip Coupler

贵 司 料 号 YOUR PART NO.: _____

敝 司 料 号 OUR PART NO.: MGMC18H2G4506-C63

版 本 号 VERSION.: V1.0

接受 RECEPTION

THE SPECIFICATION HAS BEEN ACCEPTED.

该纳入仕様书已被我司接受

日期:
DATE:

公司:
COMPANY:

批准
CFMD

审核
CHKD

接收
RCVD

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纳入仕様书改定履历 **MODIFY HISTORY OF SPECIFICATION**

NO.	DATE	CONTENT	APPROVED
1	2016.08.17	初稿 Constitute	梁启新

目录 CATALOG

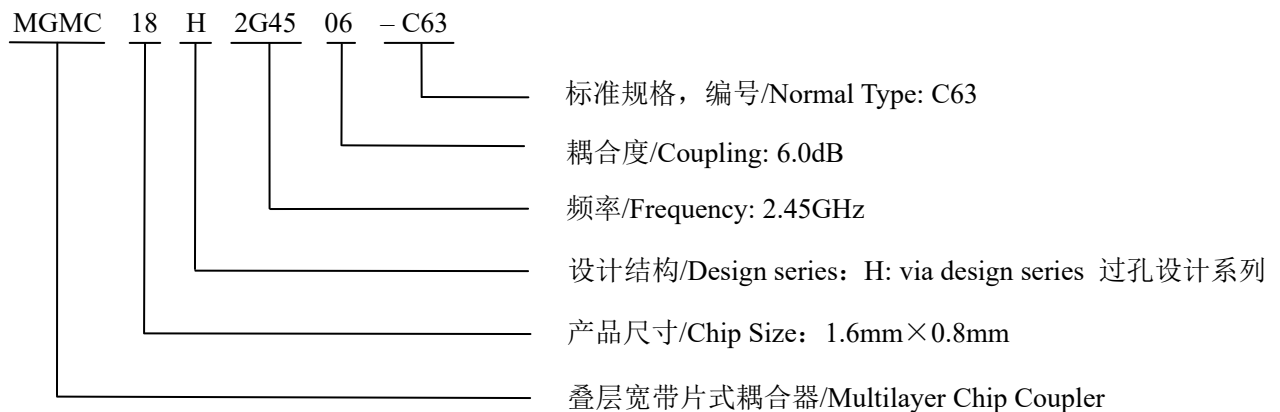
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1 适用范围 Scope

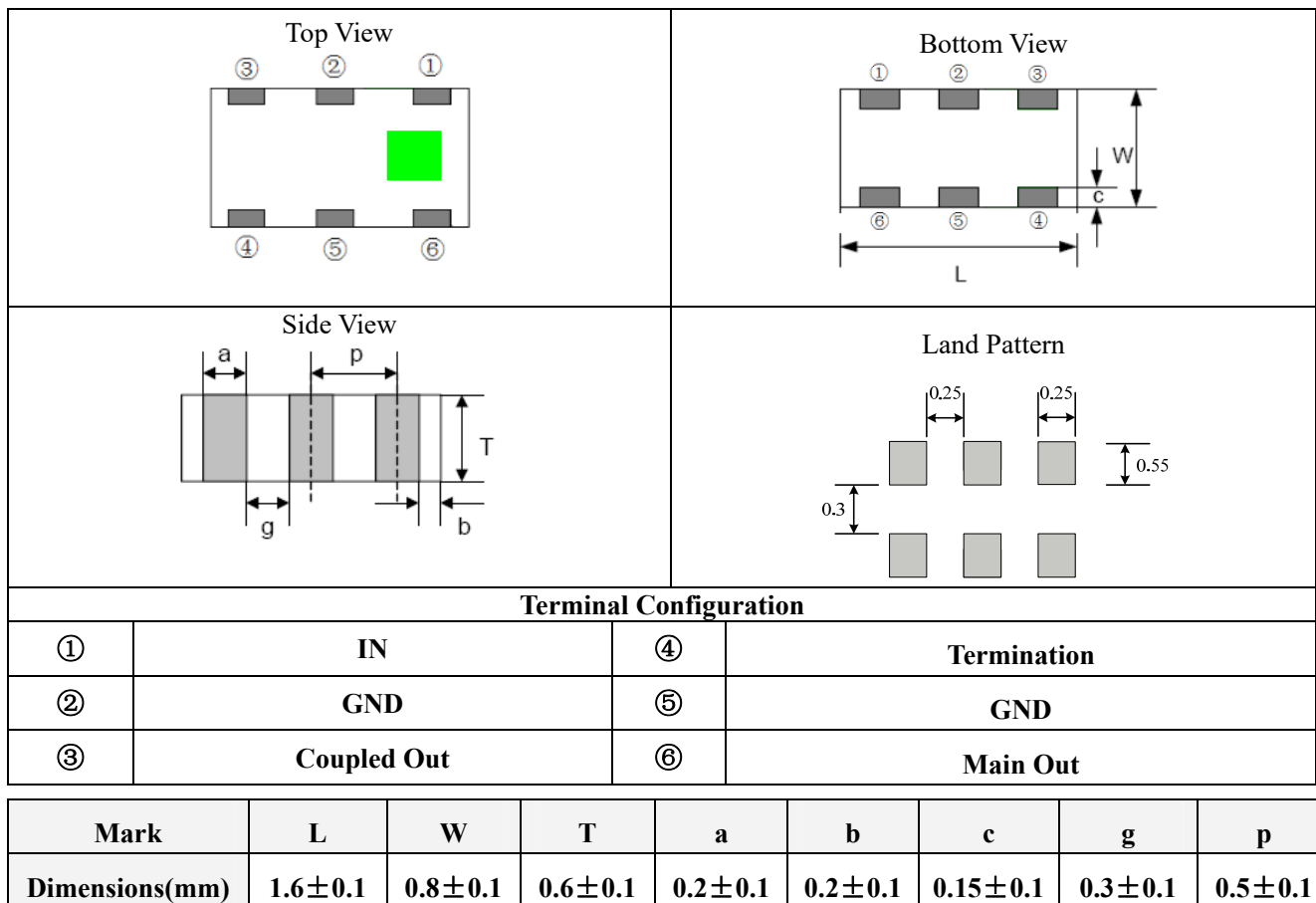
“麦捷”叠层片式耦合器系列产品设计用于小灵通，GSM/DCS/PCS 手机，无线局域网卡和蓝牙模块等，具有低的插入损耗、高的隔离度和小体积 SMD 片式设计，能减少复杂的调校工作，可以简化电路设计。

“Microgate” Multilayer chip coupler series are designed to be used in PHS/GSM/DCS/PCS phones, Wlan card, Bluetooth modules with low insertion loss and high isolation as well as small size SMD chip design , which can simplify your complex tuning and circuit design .

2 品名构成 Product Identification



3 形状和尺寸 Appearance and Dimensions



4 测试条件 Testing Conditions

除非另有规定，否则在以下条件下测试 <Unless otherwise specified>

温度 Temperature : Ordinary Temperature (5 to 35℃)
 湿度 Humidity : Ordinary Humidity (25 to 85% RH)

大气压强 Atmospheric Pressure : 86 to 106 kPa

当对测量结果有疑问时<In case of doubt>

温度 Temperature : 20±2℃
 湿度 Humidity : 60 to 75% RH
 大气压强 Atmospheric Pressure : 86 to 106 kPa

5 电气性能 Electrical Characteristics

操作温度范围 Operating Temperature Range : -40 to +85℃

保存温度范围 Storage Temperature Range : -40 to +85℃

Frequency Range(MHz)	Insertion Loss(dB)	VSWR	Coupling (dB)	Isolation (dB)	Power Capacity
2400~2500 MHz	1.80 Max.	1.5 max.	6.5±1.0	30 min	2W max.

6 焊接条件 Recommended Soldering Conditions

1、焊剂 Flux, Solder

① 使用松香助焊剂，禁止使用卤化物含量超过 0.2wt% 的强酸性助焊剂。

Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).

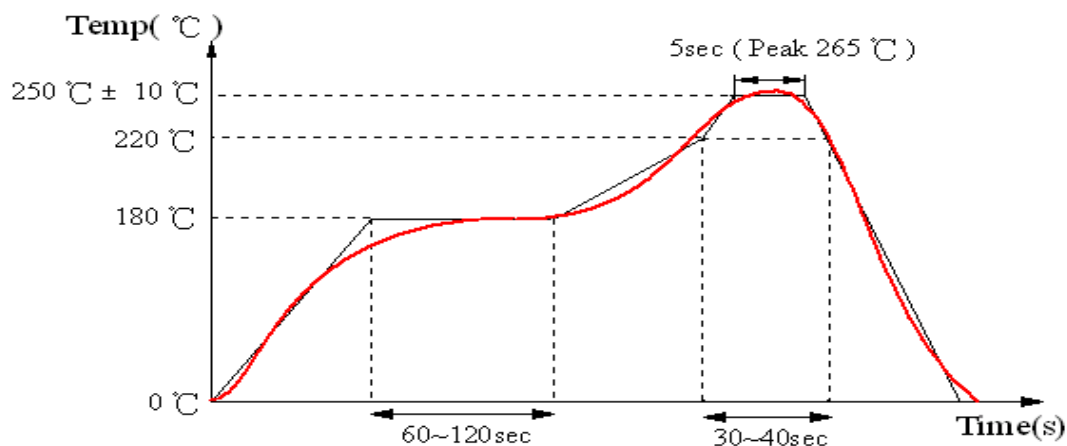
② 使用纯锡焊料 Use Sn solder.

2、回流焊条件 Reflow soldering conditions

● 预热时，产品表温与焊料温度的温差最大不允许超出 150℃，焊接完后冷却时，产品表温与溶剂温度之间的温差最大不允许超出 100℃。预热不足有可能引发产品表面裂纹，导致产品品质下降。

Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150℃ max. Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100℃ max. Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.

● 标准回流焊曲线 Standard soldering profile.



3、手工返工 Reworking with soldering iron

当使用电烙铁进行手工焊接时，以下条件必须严格遵守 The following conditions must be strictly followed when using a soldering iron.

预热 Pre-heating	150℃, 1 minute
尖端温度 Tip temperature	350℃ max
输出功率 Soldering iron output	80w max
电烙铁头尖端尺寸 End of soldering iron	φ3mm max
焊接时间 Soldering time	3 seconds max